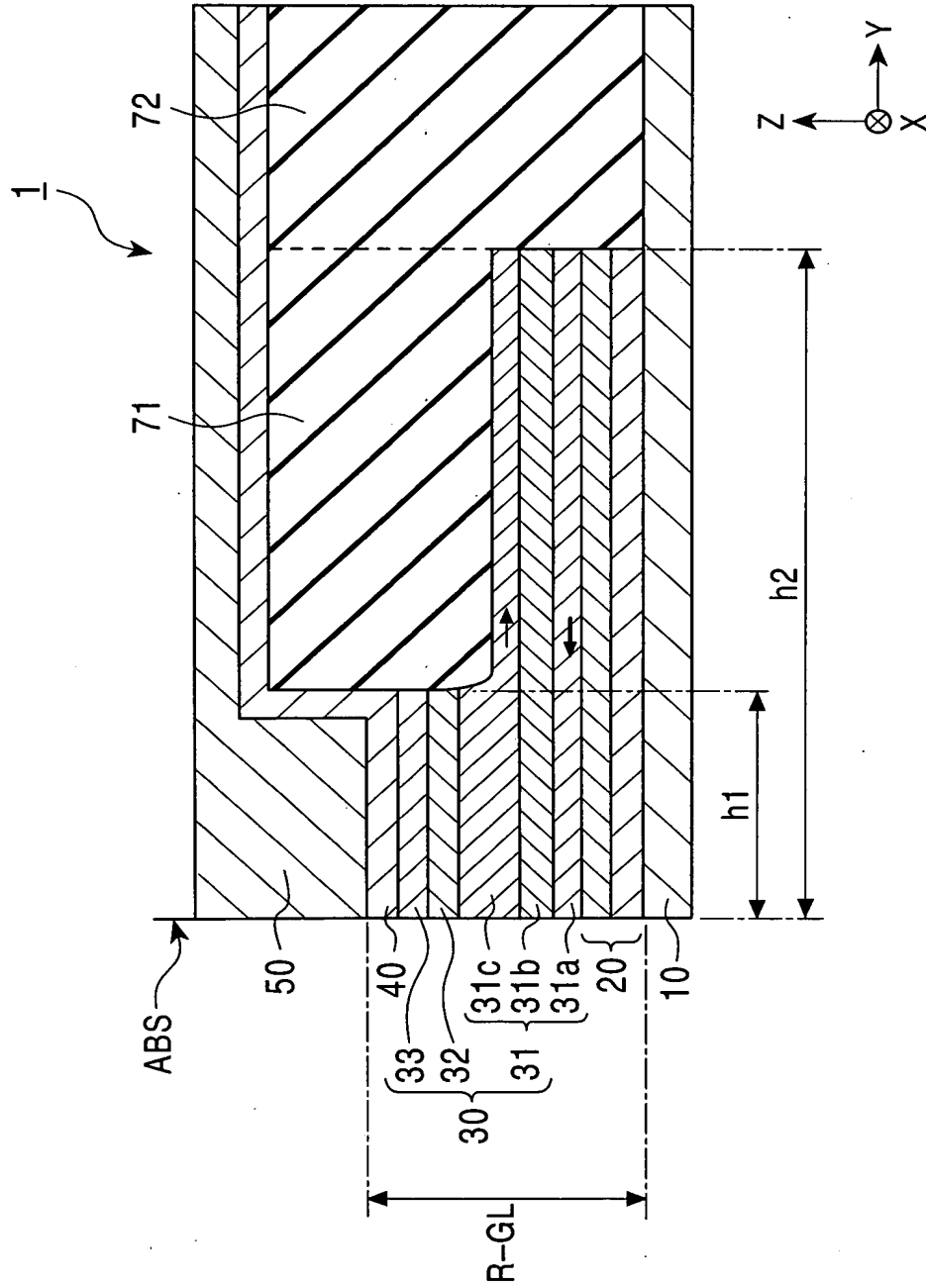


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FIG. 1



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FIG. 2

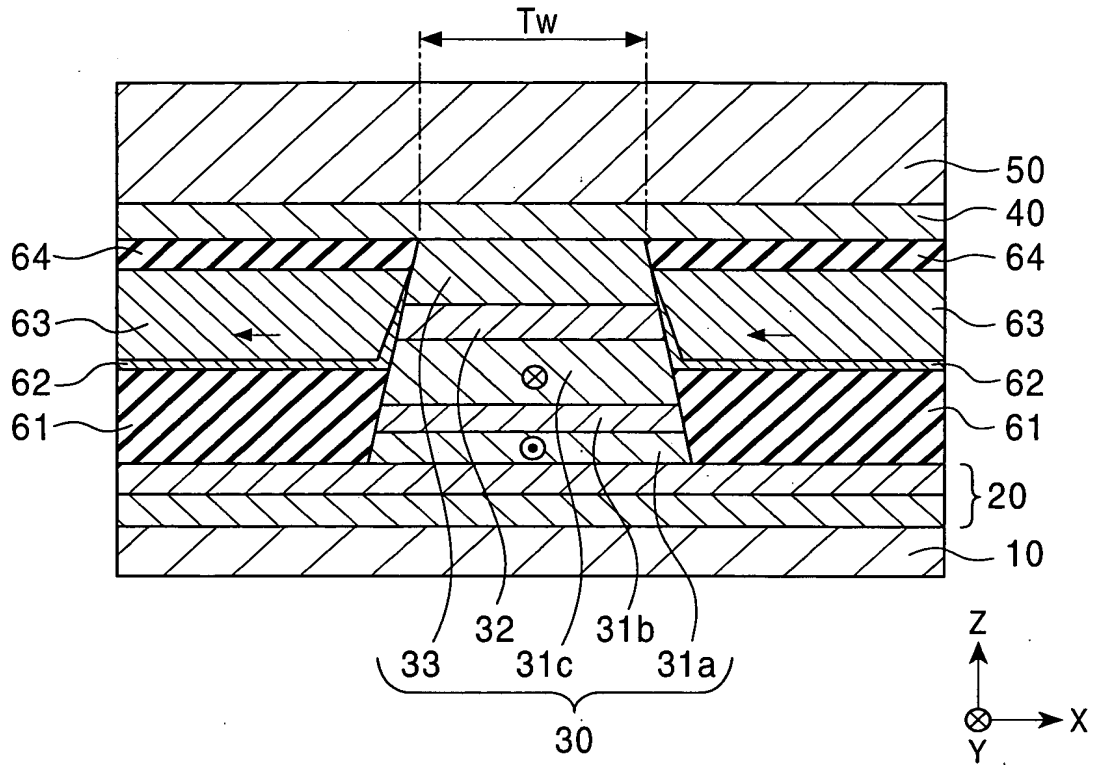
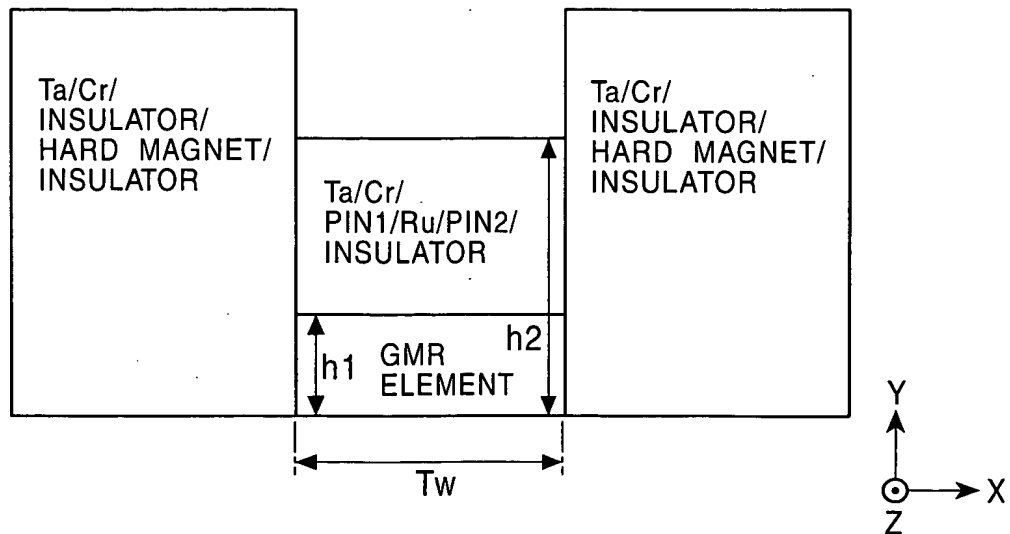
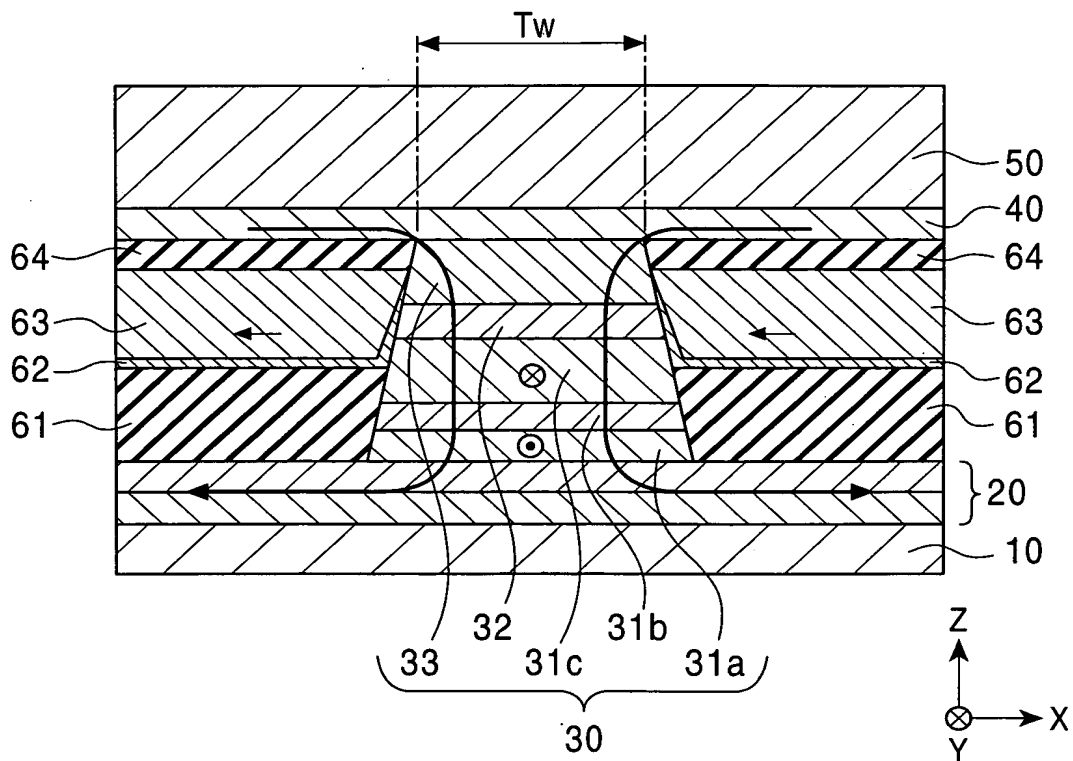


FIG. 3



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FIG. 4



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FIG. 5A

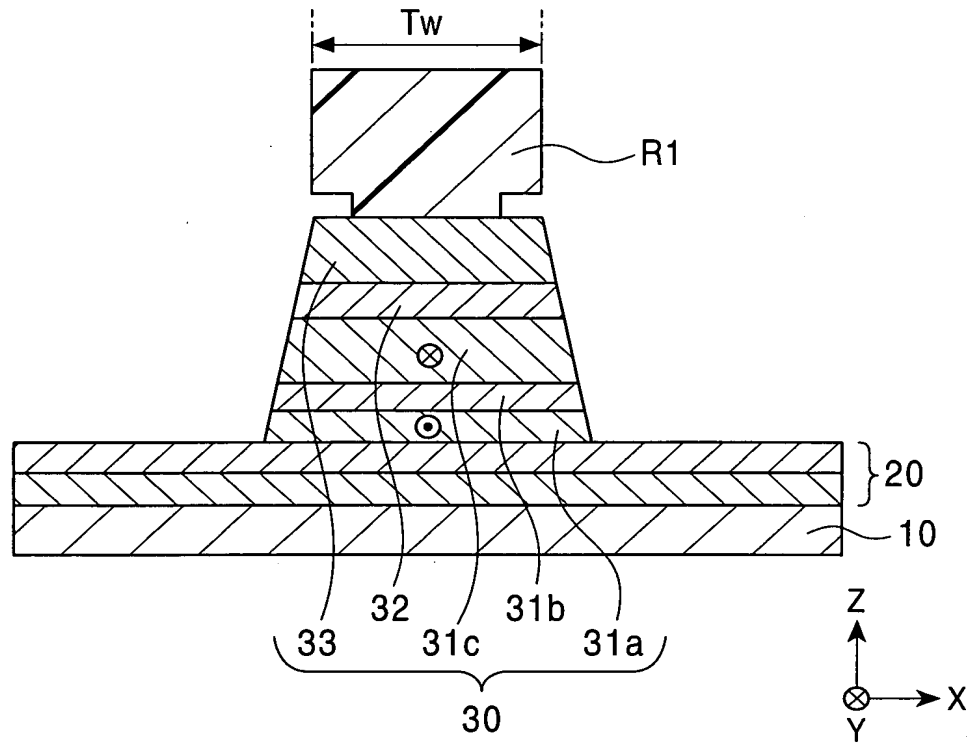
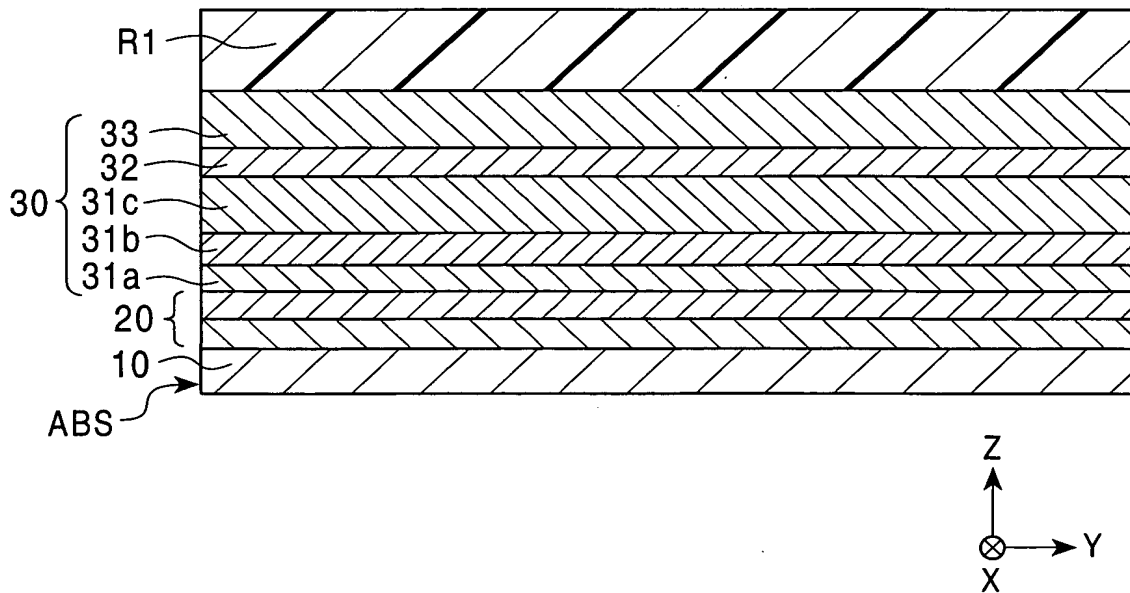


FIG. 5B



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FIG. 6A

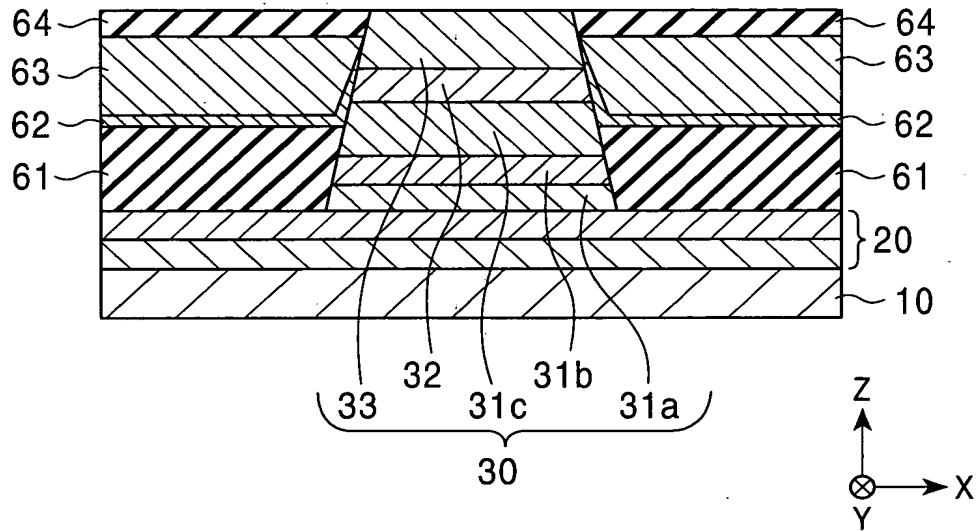


FIG. 6B

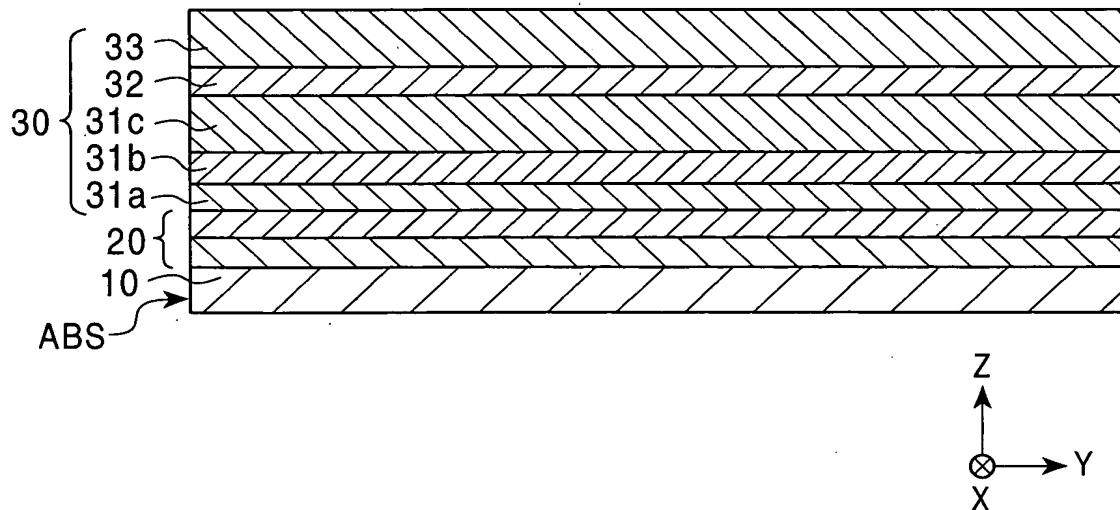


Figure 7A is a cross-sectional view of a semiconductor device 7A. The device consists of a substrate 10 with a stack of layers 20. The stack of layers 20 includes layers 61, 62, 63, and 64. A layer 71 is disposed on top of the stack of layers 20. A layer R2 is disposed on the side of the stack of layers 20. A layer 30 is disposed on the top surface of the stack of layers 20. The layer 30 includes sub-layers 31a, 31b, 31c, 32, and 33. A coordinate system is shown with the Z-axis pointing up, the X-axis pointing right, and the Y-axis pointing out of the page (indicated by a circle with a cross).

This cross-sectional diagram illustrates a vehicle body panel assembly. A base layer, labeled 10, is made of ABS (Acrylonitrile Butadiene Styrene). Above this base are several layers forming a decorative or functional skin, collectively labeled 20. These layers include a bottom layer 10, followed by layers 31a, 31b, 31c, 32, and 33. The topmost part of this stack is a textured surface 71. A specific section of the assembly, indicated by bracket 30, has a thickness denoted as h1. On the left side, a component R2 is shown, which appears to be a fastener or clip used to secure the layered structure.

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FIG. 8A

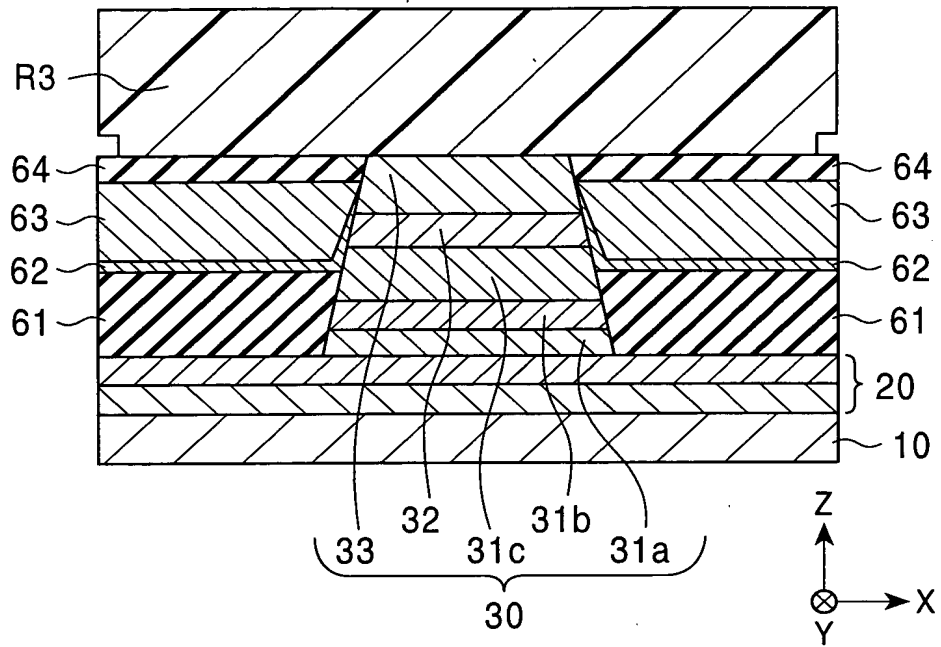


FIG. 8B

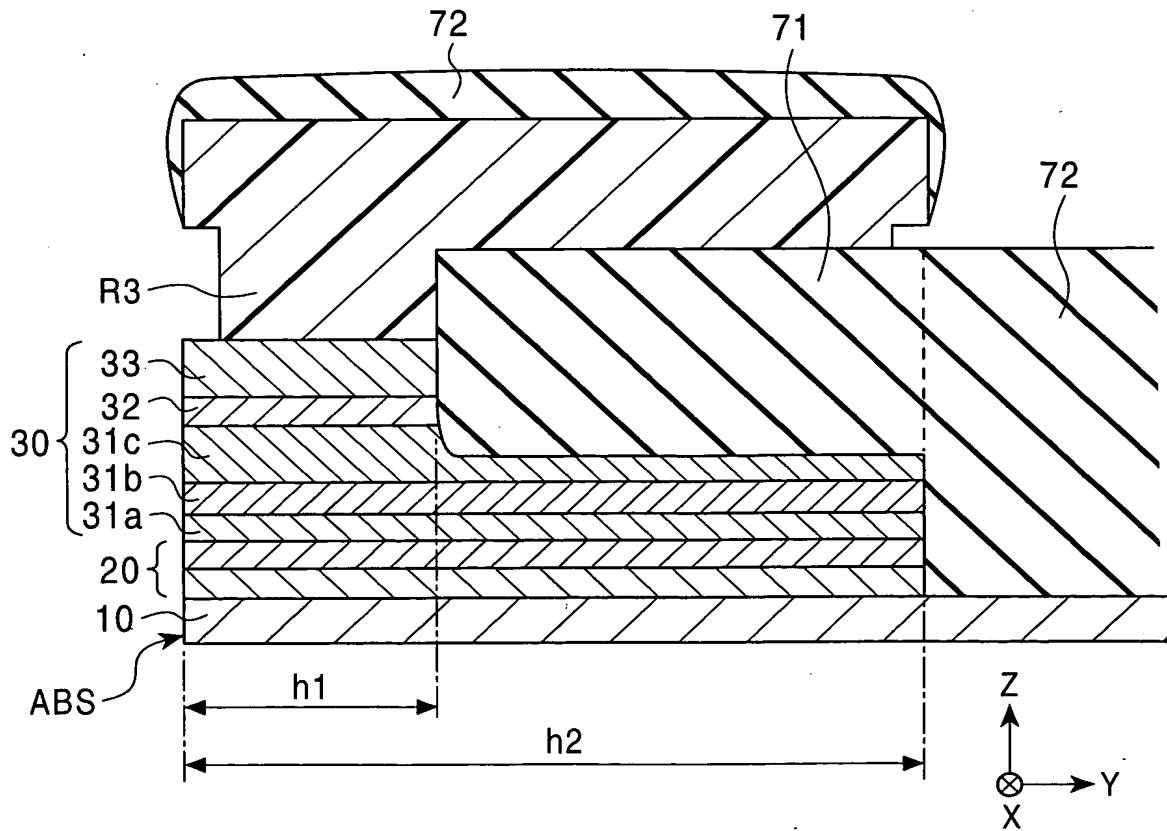
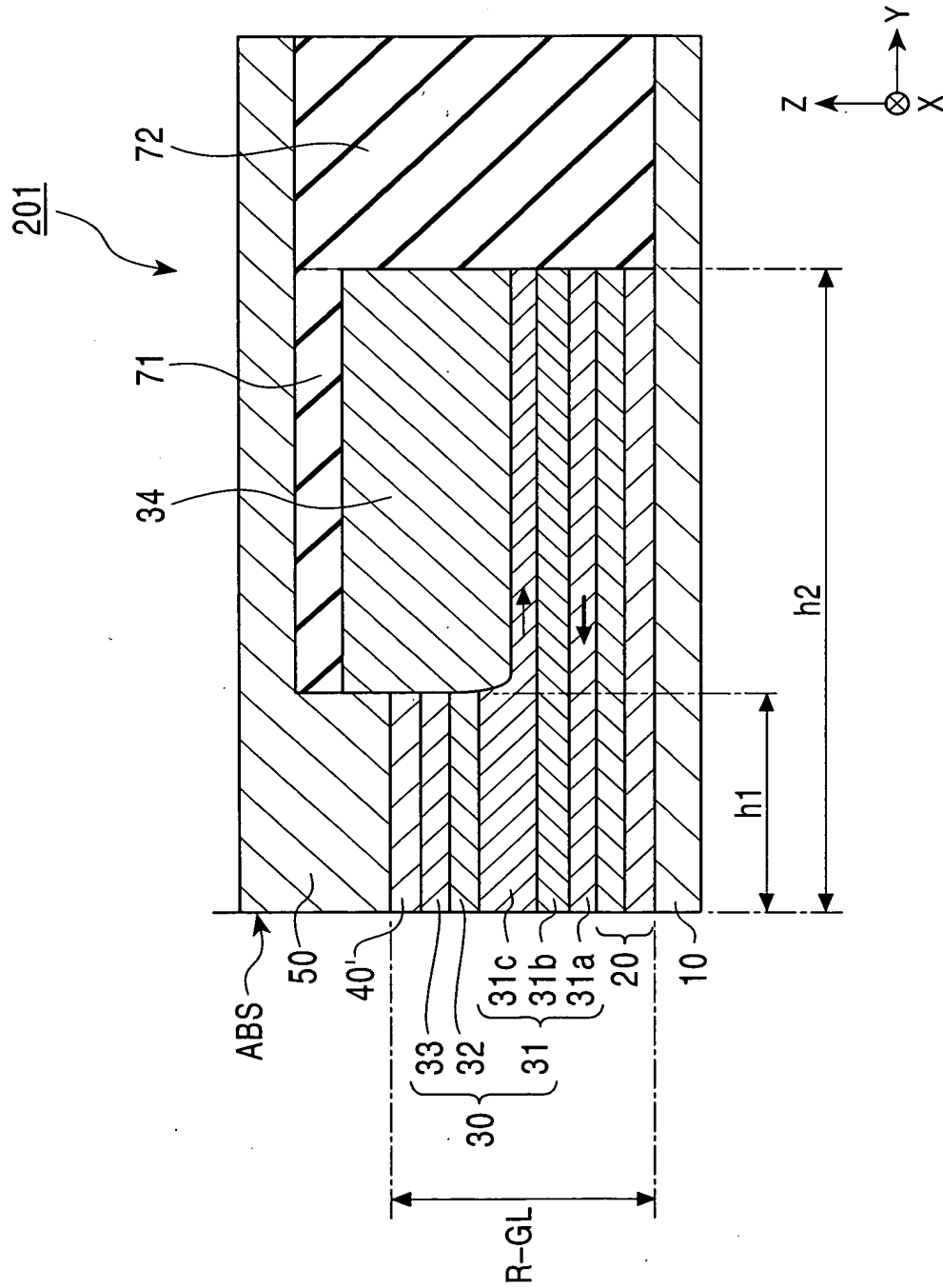


FIG. 9



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FIG. 10

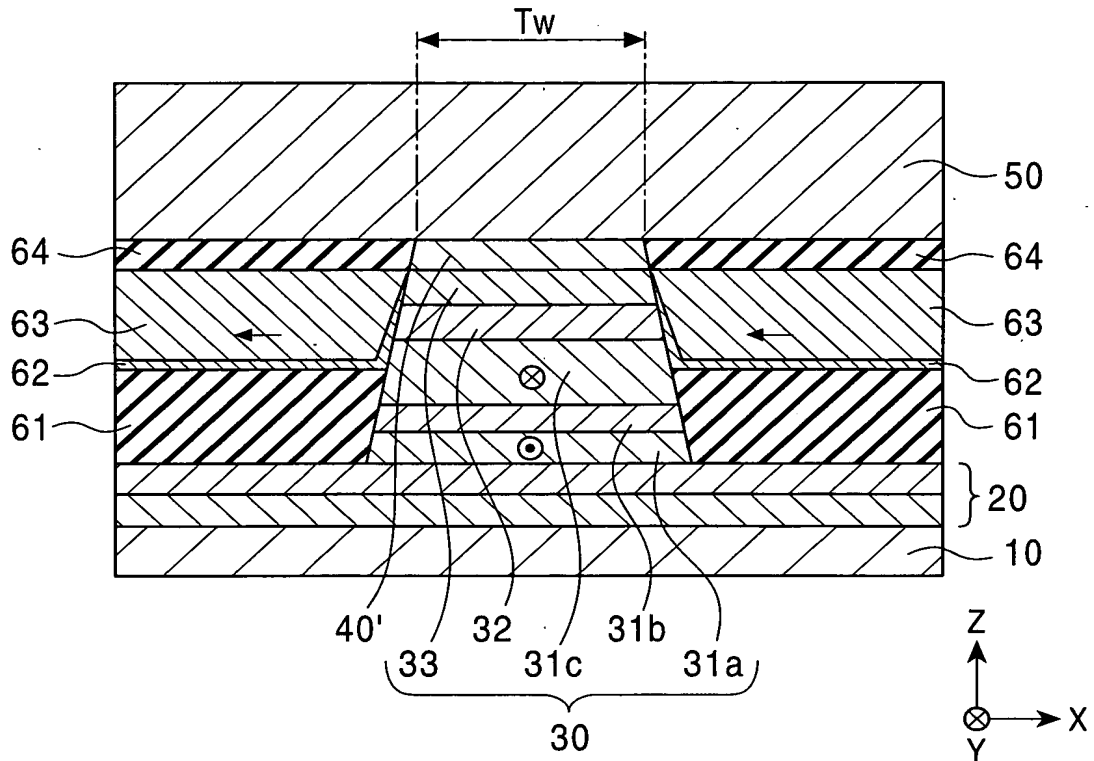


FIG. 11

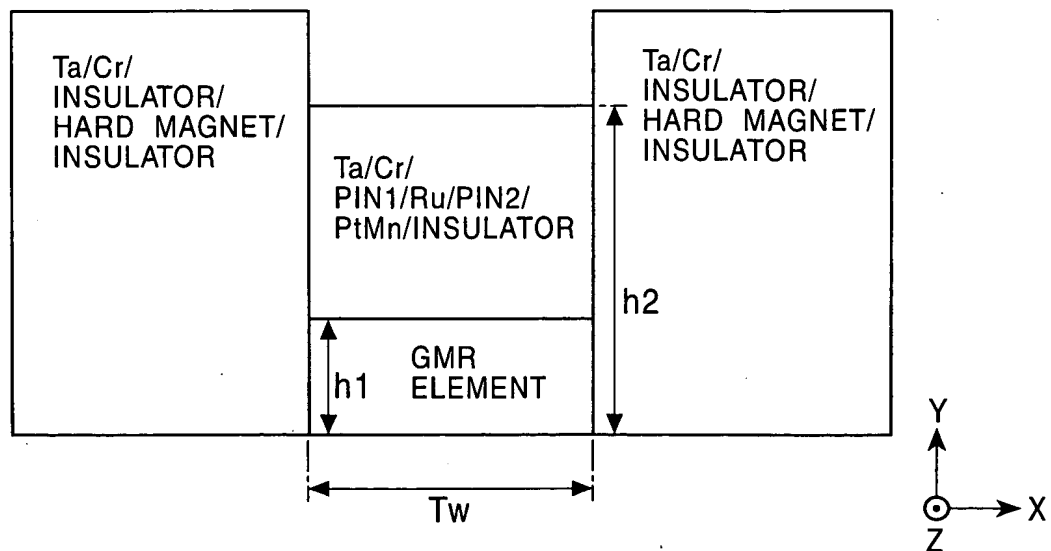


FIG. 12A

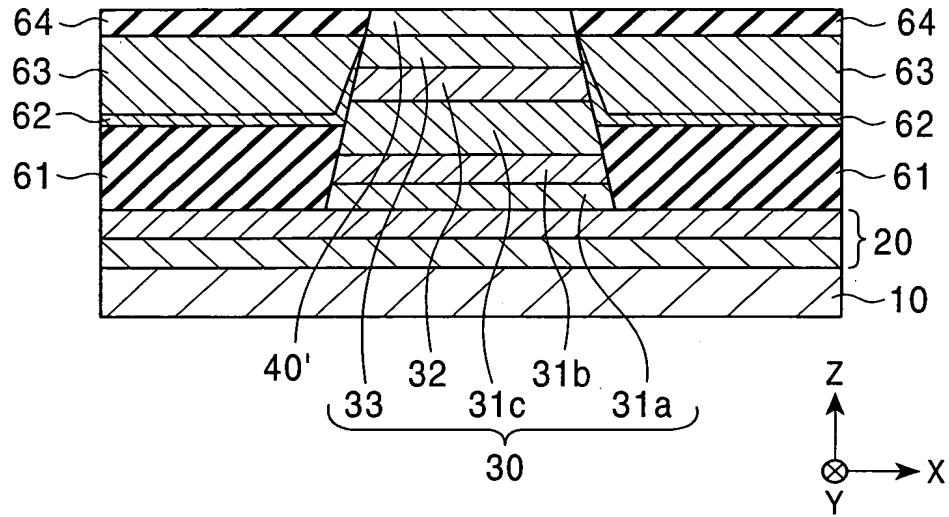


FIG. 12B

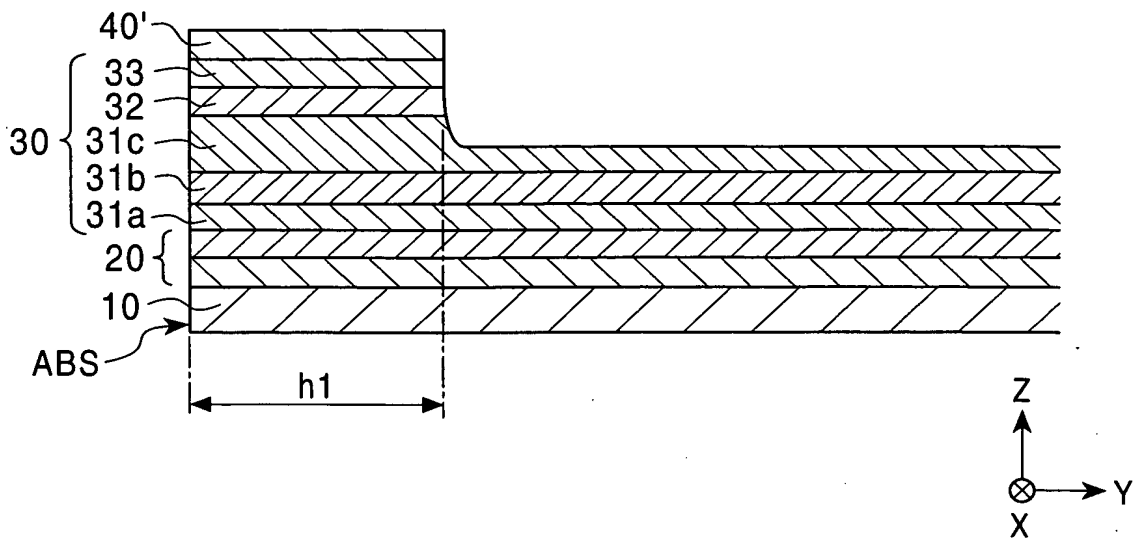


FIG. 13A

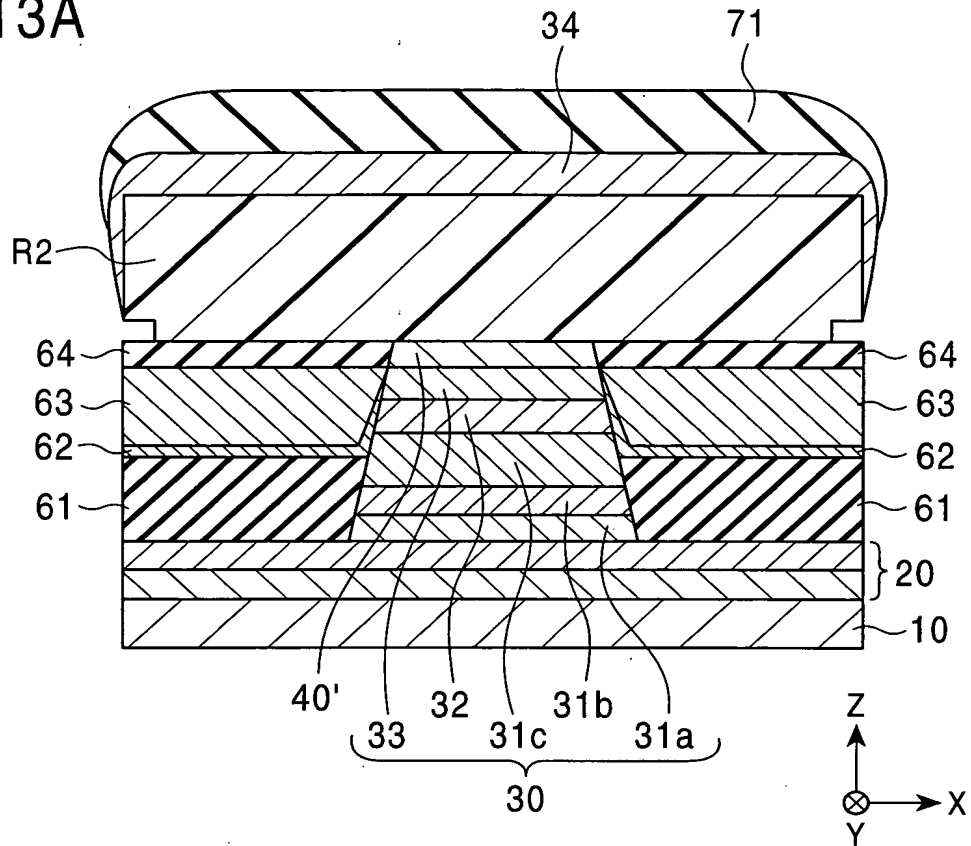
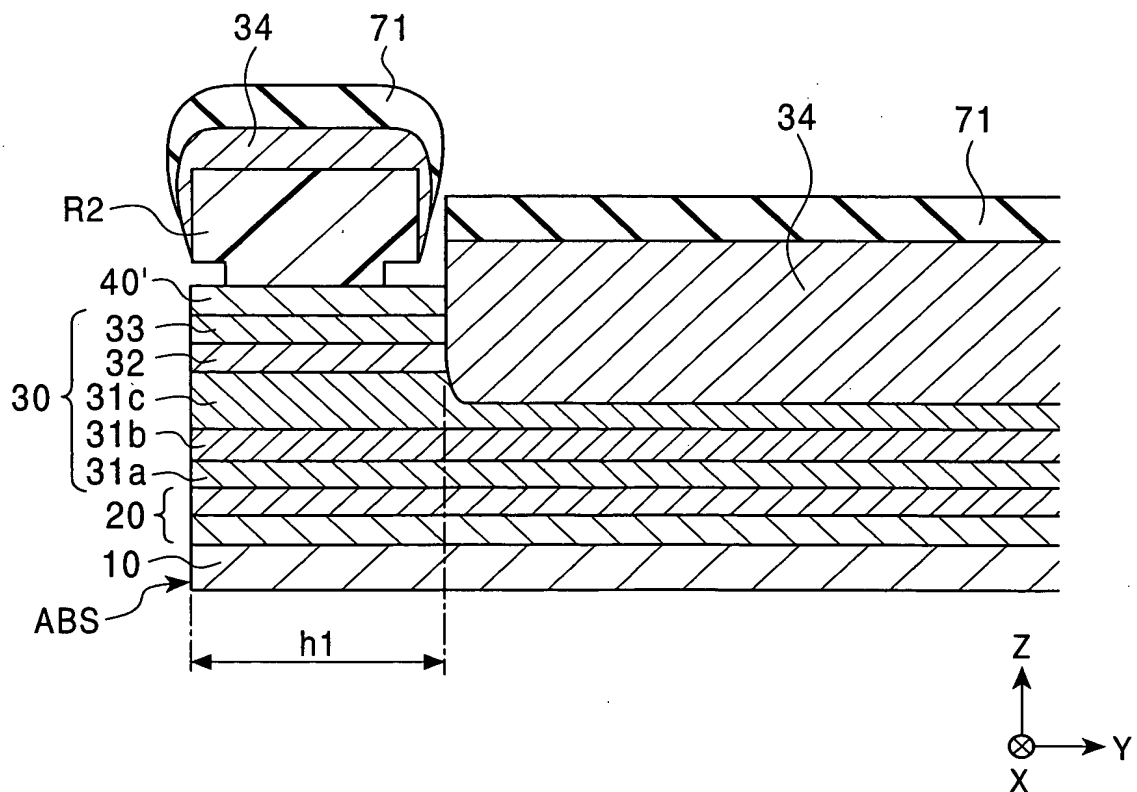
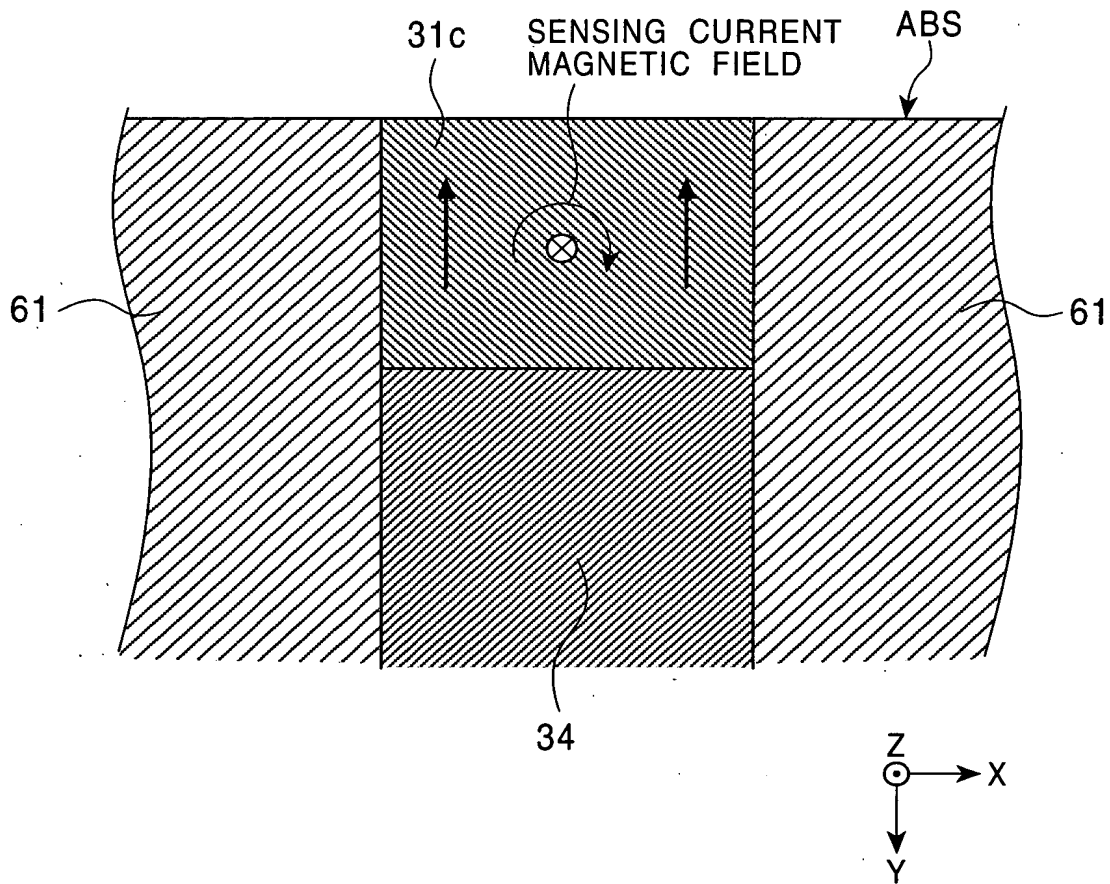


FIG. 13B



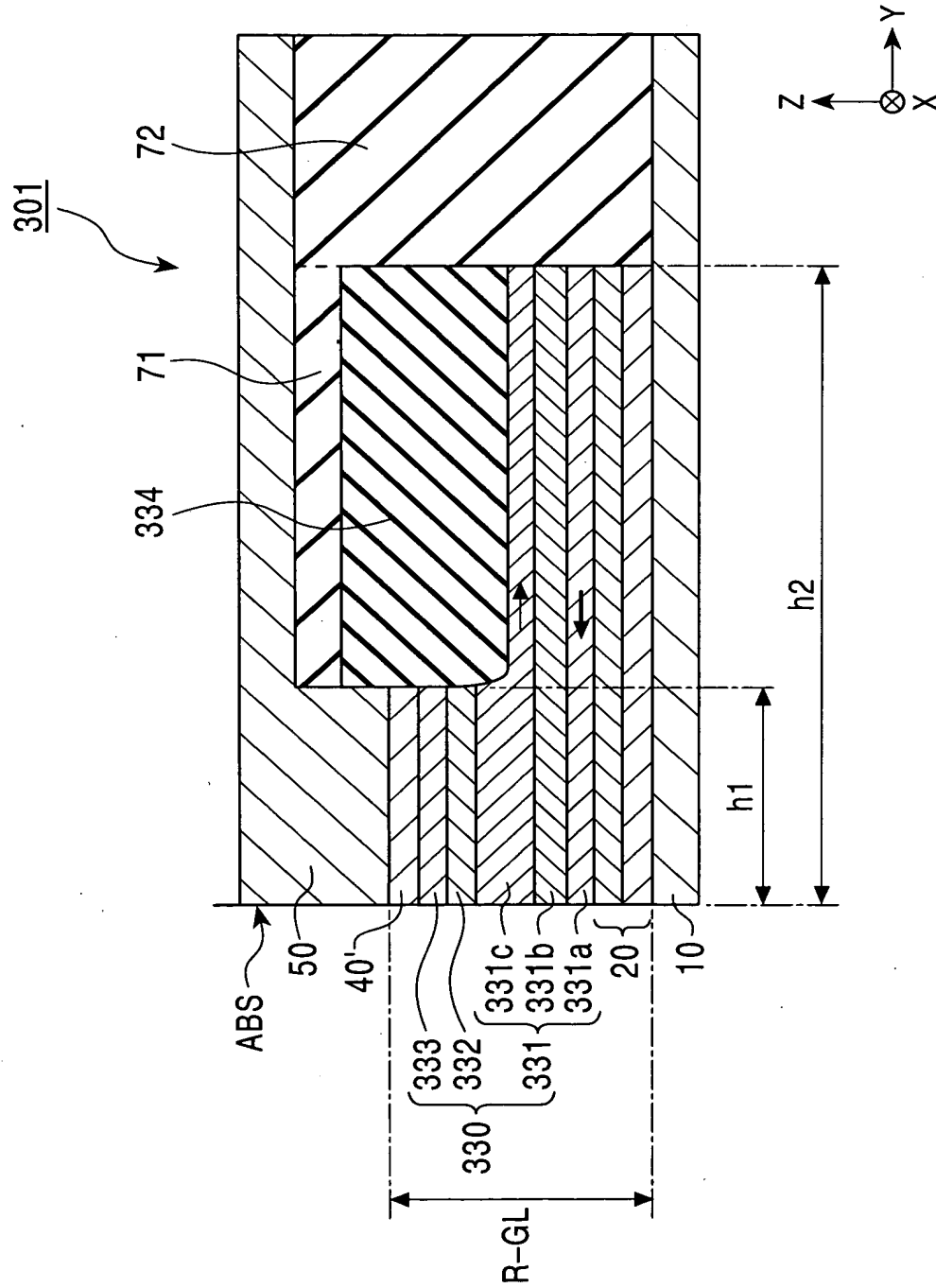
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FIG. 14



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FIG. 15



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FIG. 16

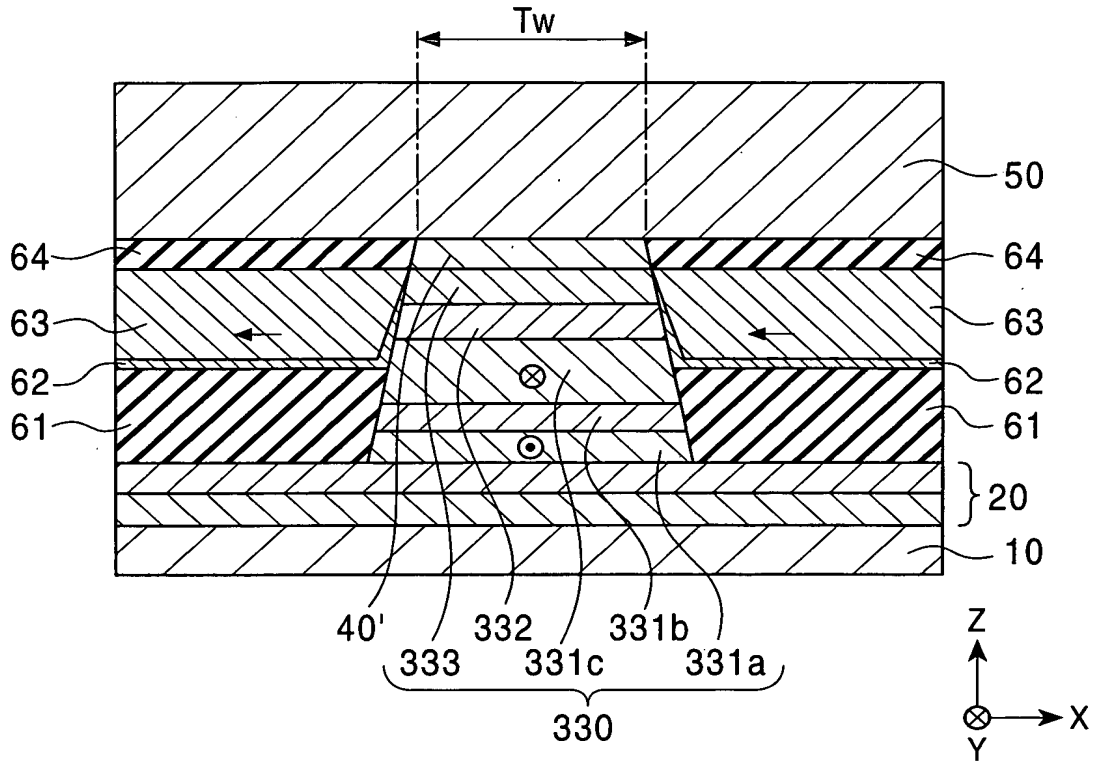
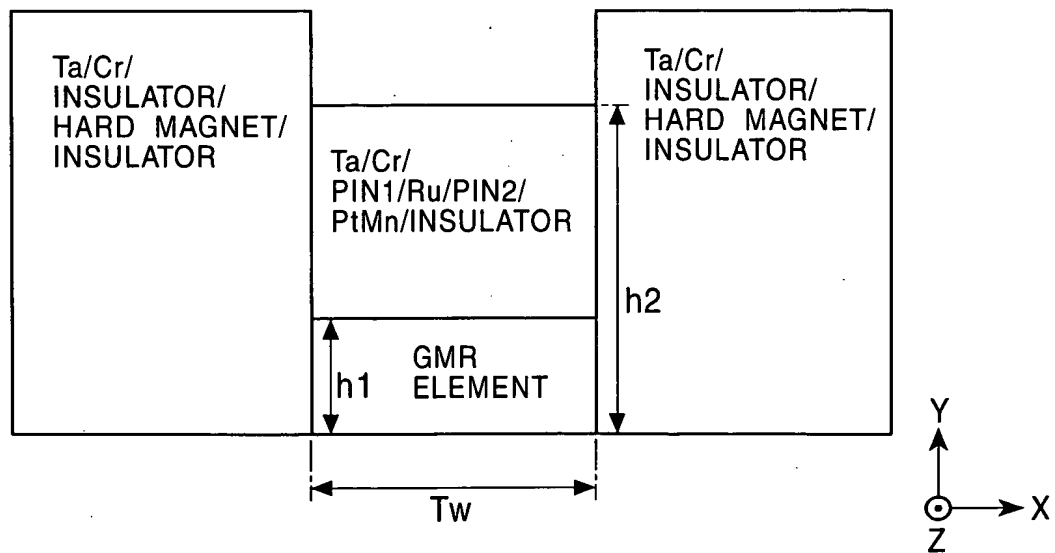
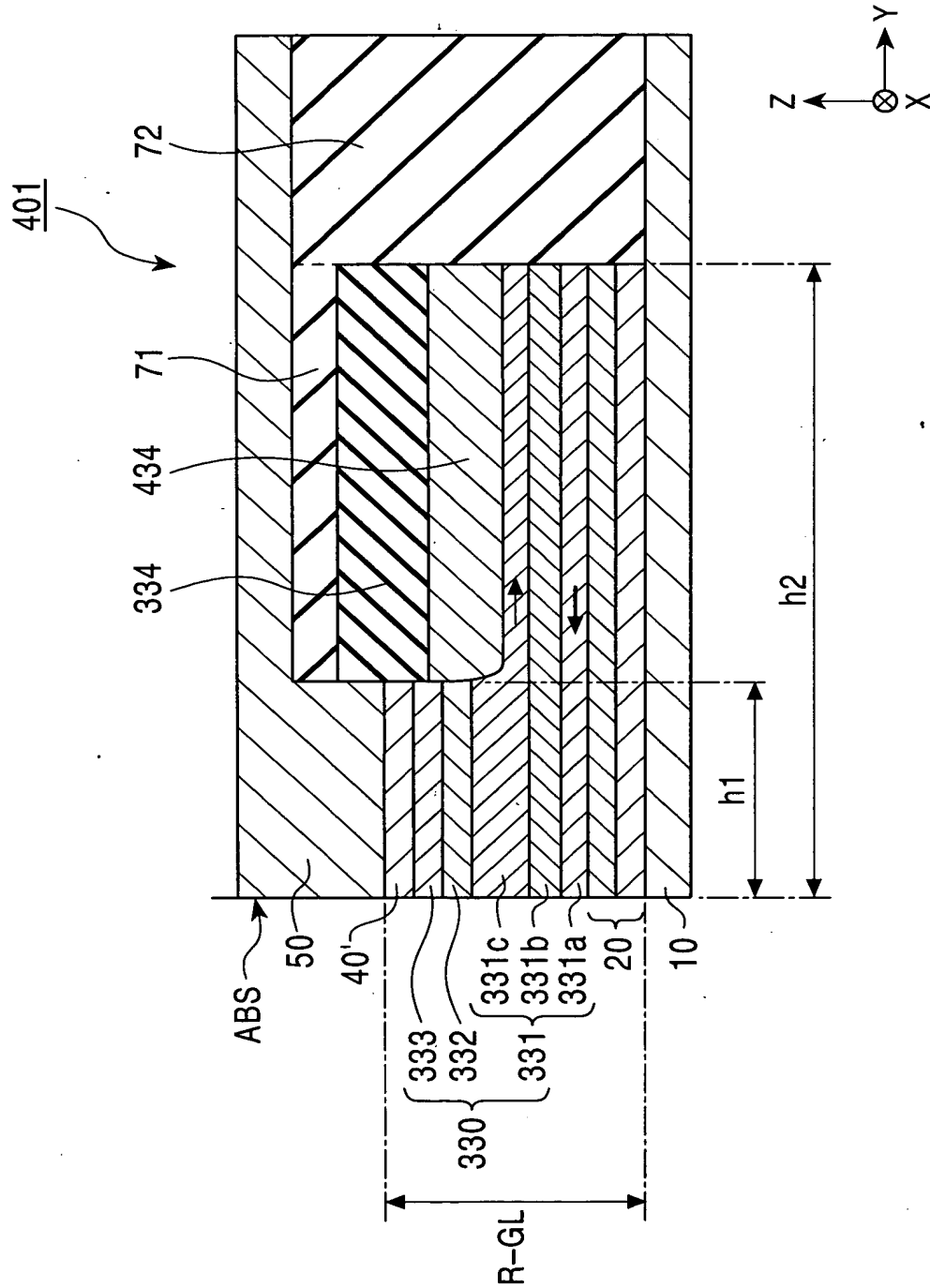


FIG. 17



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FIG. 18



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FIG. 19

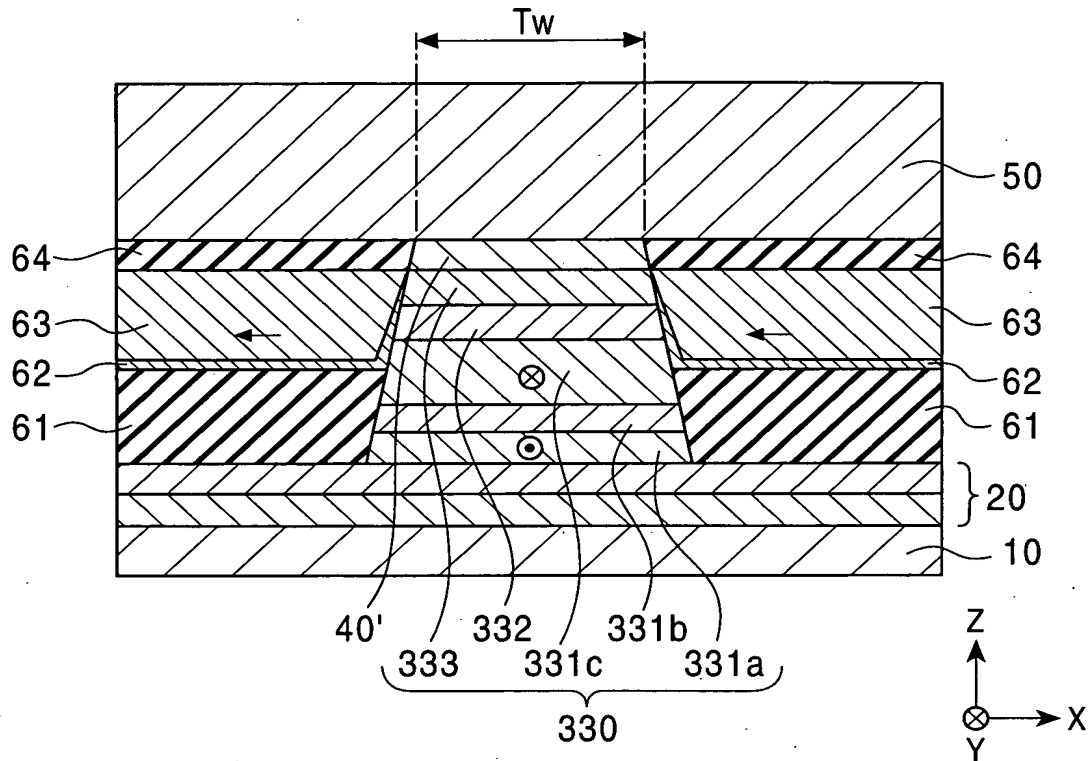
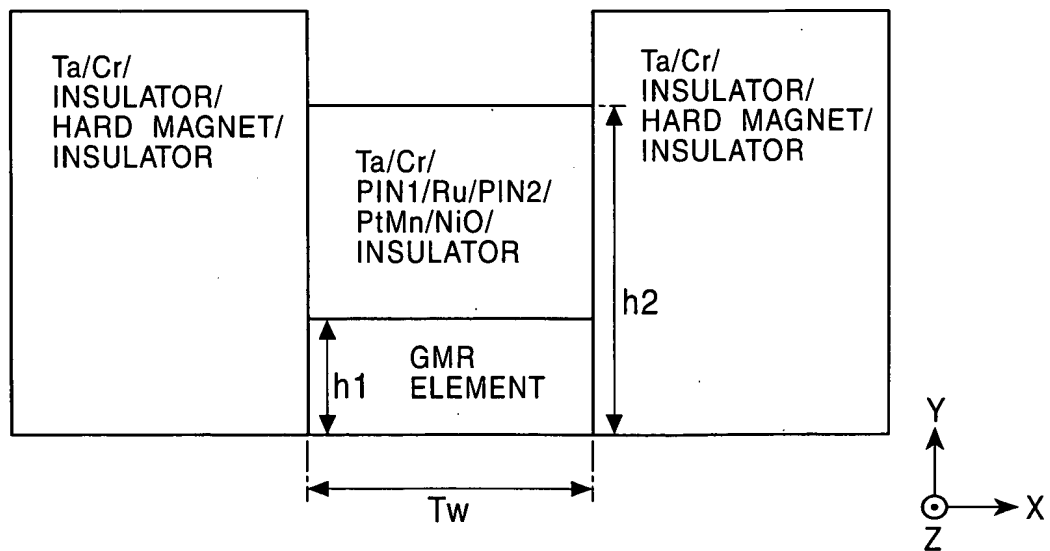


FIG. 20



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FIG. 21
PRIOR ART

